

SOT316-1

plastic shrink quad flat package; 208 leads (lead length 1.3 mm); body 28 x 28 x 3.4 mm; high stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	SQFP208
Package type industry code	SQFP208
Package style descriptive code	SQFP (shrink quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-029
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	4.1	4.1	mm
A ₂	package height	3.2	-	3.4	3.6	mm
n ₂	actual quantity of termination	-	-	208	-	

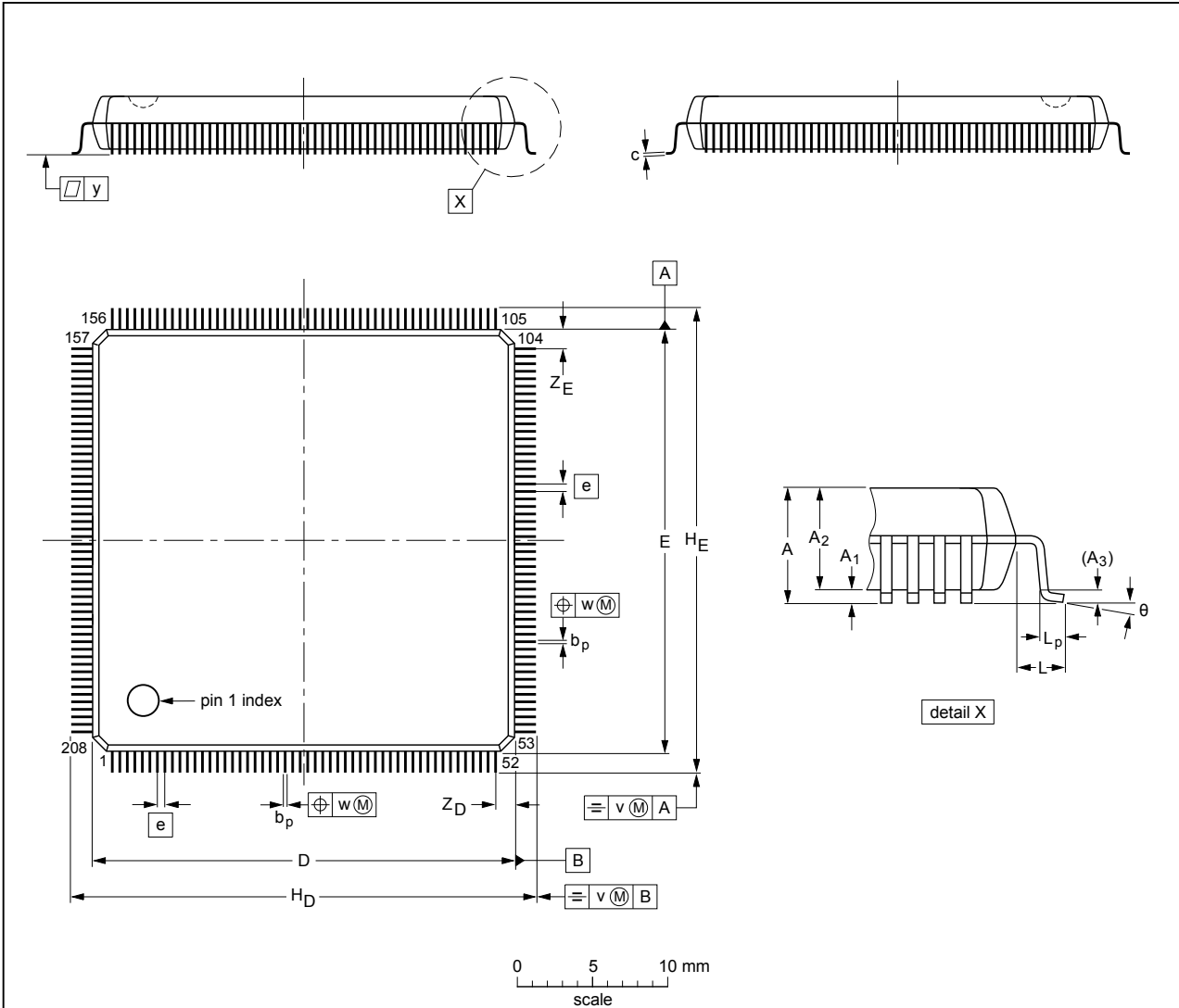


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2. Package outline

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	4.1	0.50 0.25	3.6 3.2	0.25	0.27 0.17	0.20 0.09	28.1 27.9	28.1 27.9	0.5	30.9 30.3	30.9 30.3	1.3	0.75 0.45	0.2	0.08	0.08	1.39 1.11	1.39 1.11	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT316-1		MS-029			00-01-25 03-02-25

Fig. 1. Package outline SQFP208 (SOT316-1)

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3. Soldering

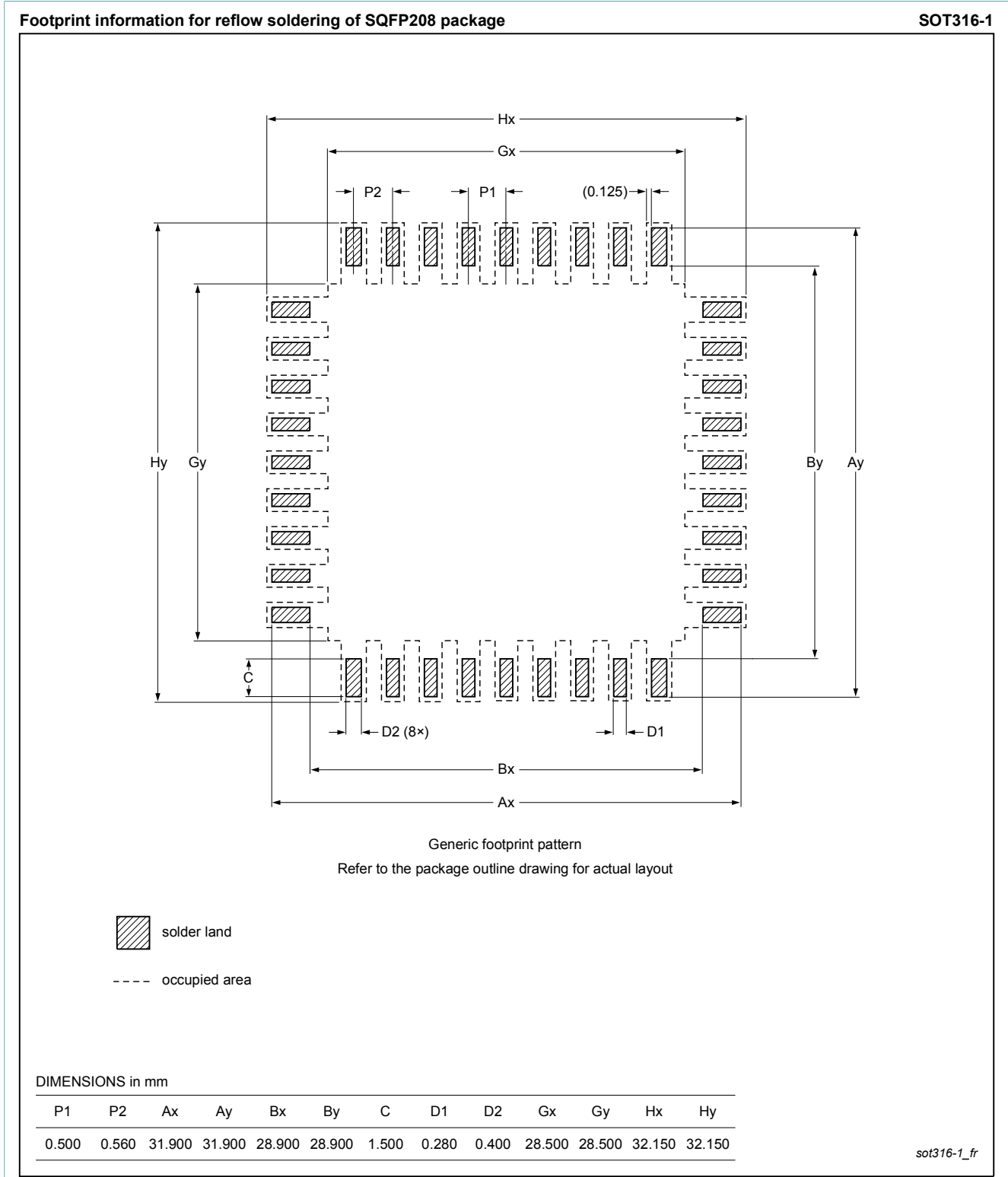


Fig. 2. Reflow soldering footprint for SQFP208 (SOT316-1)

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4. Legal information

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